Entegris

From Back-End Commodity to Performance Driver: The Strategic Role of Advanced Semiconductor Packaging in Automotive and ADAS Systems



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Abstract
Advanced semiconductor packaging has emerged as a critical bottleneck and differentiator in the global semiconductor industry at a time when demand for compute, bandwidth, and energy efficiency is rising across multiple sectors. While front-end scaling is slowing and becoming increasingly capital-intensive, advanced packaging enables continued system-level performance gains through heterogeneous integration, chiplets, and multi-die architecture.

From a macroeconomic perspective, this shift intersects with several structural trends:
• the global race for semiconductor competitiveness and supply-chainresilience,
• increasing geopolitical concentration of advanced packaging capacity,
• and accelerating digitalization of industries such as automotive, AI, andindustrial automation.

In automotive in particular, the transition toward software-defined vehicles and higher levels of driver assistance concentrates computing power into fewer, more capable electronic control units. This amplifies the importance of packaging technologies that can deliver high bandwidth, low latency, robust thermal behavior, and automotive-grade reliability—making advanced packaging a strategic topic not only for engineers, but also for executives responsible for sourcing, operations, and long-term competitiveness.

Biography
Marco Paul is a Senior Expert at Porsche Consulting, specializing in semiconductor strategy, innovation and industrialization. His work spans smart-factory transformation, emerging semiconductor technologies - including wide-bandgap semiconductors and advanced packaging - and the semiconductor requirements of AI-enabled physical systems in automotive and robotics. He represents Porsche Consulting on SEMI Smart Manufacturing and has authored industry perspectives on semiconductor strategy, silicon carbide and advanced packaging. Marco holds an M.Eng. in Mechanical Engineering and an Executive MBA and combines technical depth with a strategic perspective on translating emerging technologies into scalable industrial and business impact.

Jonas Altmann is a Senior Manager at Porsche Consulting specializing in technology strategy, R&D transformation, and innovation-driven operating model design. His expertise spans corporate technology strategies, organizational transformations, technology ecosystems, and international partnerships. With extensive experience across the automotive industry, China, and Southeast Asia, he focuses on innovation ecosystems, technology partnerships, and the development of future-ready R&D organizations and operating models. Jonas participates in the SEMI Global Automotive Advisory Council and holds an M.Sc. in Aerospace Engineering, combining deep technical expertise with broad experience in technology.

References

Materials Matter: Enabling Advanced Packaging Performance at Scale



G. Parry
Director | Advanced Innovation & Technology
Entegris, Moirans, France

Abstract
As advanced packaging becomes the primary path to **system-level performance**, success increasingly depends on how well materials and interfaces are controlled throughout the integration flow. The shift to **heterogeneous integration**, high-density interconnects, and advanced bonding schemes places new requirements on material purity, stability, and interaction at various technology nodes.

Performance is now tightly linked to **interface integrity**, where contamination, defects, or variability can directly impact **yield and long-term reliability**. At the same time, increasing thermal loads and new architectures require materials with enhanced thermal conductivity, electrical performance, and compatibility with emerging integration schemes.

Scaling these technologies from development to **high-volume manufacturing** introduces additional challenges in handling, cleaning, planarization, and process consistency – particularly with the transition toward larger formats such as panel-level packaging.

Entegris supports this evolution through **materials-driven solutions** and process-enabling technologies spanning Cu deposition, cleaning, CMP, high-viscosity material handling, thermal management, contamination control, and filtration – ensuring that performance achieved at the design stage is preserved through industrial-scale manufacturing.

Biography
Gilbert Parry joined Entegris in 1995 as an application engineer in its semiconductor business. He then held various technical and product management positions in gas purification, liquid and specialty chemicals filtration.

Over the past 20 years, Mr. Parry has been responsible for cross-divisional Business Development activities in a variety of industries, including energy production and storage, graphic arts, water treatment or life sciences. Now involved in analyzing semiconductor technology trends to guide the company's investments and research directions, M. Parry explores the opportunities presented by the most critical applications of Advanced Packaging, particularly those requiring new materials.

Mr. Parry is a graduate engineer (Master of Science) in chemistry, polymers and materials from ECPM, Strasbourg, France.

References



W. Yang
VP of Marketing
Entegris Inc., Billerica, United States of America

Biography
Wenge Yang, Ph.D.
Vice President, Market Strategy

Dr. Yang joined Entegris in 2012 to serve as leader of Entegris Market Strategy. In his role, he is responsible for product and market strategy, market research and market trend analysis, strategic marketing, and maintenance of the company's strategic technology roadmap.
Prior to joining Entegris, Dr. Yang was an equity research analyst at Citigroup covering the semiconductor equip-ment and materials sector. He also served in various executive roles at Advanced Micro Devices, Tokyo Electron and two start-up companies.
Dr. Yang received a Ph.D. in Materials Science and an MBA from Rensselaer Polytechnic Institute, a Master of Science degree in mechanical engineering from the New Jersey Institute of Technology and a Bachelor of Science degree in materials science and engineering from Shanghai Jiao Tong University.

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A. Miller
Department Director, 3D and Silicon Photonics Technology
imec, 3D and Silicon Photonics Technology,
Leuven, Belgium

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Biography
Andy Miller graduated from the University of Glasgow in 1995 with a Honours degree in Physics. He immediately started work as a process engineer at NEC Semiconductors (UK) Ltd in lithography. In 2000 he moved to Filtronic Compound Semiconductors Limited as lead lithography engineer. In 2008 he joined the Advanced Lithography program at IMEC, focused on alternative materials for Double Patterning.

In 2009 he became the Team Leader for More Than Moore lithography development at imec, quickly expanding the team to include wafer level bonding, die bonding and metrology. In 2012 he took up the position of Group Leader for technology development within the 3D Integration program, becoming department Department Director for 3D and Si Photonics technology development at imec in 2020. Since 2026 he has been head of the 3D and Advanced Packaging Technology Office at IMEC.

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C. Huyghebaert
CTO
Black Semiconductor, Aachen, Germany

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Biography
Cedric Huyghebaert is currently Chief Technology Officer at Black Semiconductor, a German start-up that aims to develop technology to inspire the semiconductor world to rethink data transfer in advanced computing systems. He got his master degree in Physics from the UGhent. He started in 1999 as a junior researcher in the Materials and Component Analyses group at imec. He received his PhD in Physics in 2006 at the KULeuven in Belgium. In 2005 he joined imecs pilot line as a support integration engineer, especially dealing with the process contamination control. He was part of the packaging group from end 2007 till begin 2010, working as a senior integration engineer dealing with 3D-stacked IC integration. From 2010 to 2019, he led the nano-applications and –material engineering (NAME) group at imec. He guided the transition for 2D materials from lab to fab. From 2019 to 2022 he worked as Program manager of exploratory processes and modules, dealing with material exploration and early module integration for functional applications. He was the technical lead of the 2D experimental Pilot line division in the Graphene Flagship. He (co-)authored more than 250 journal and conference papers.

References

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T. Uhrmann
VP of Sales
EV Group, Sankt Florian am Inn, Austria

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Biography
Dr. Thomas Uhrmann is Vice President of Sales at EV Group (EVG), a position he assumed in 2025. In this role, he is responsible for leading EVG's global sales organization and driving growth across key markets worldwide.
Prior to his appointment as Vice President of Sales, Dr. Uhrmann served as Director of Business Development at EV Group, where he oversaw all aspects of the company's worldwide business development activities. His focus included 3D integration, Advanced Packaging, and a number of emerging markets.
He holds an engineering degree in mechatronics from the University of Applied Sciences in Regensburg and earned a PhD in semiconductor physics from the Vienna University of Technology.

References

Panelist



R. Antonicelli
Senior Director, Strategy and Businsess Innovation
STATS ChipPAC, Vaud, Switzerland

Abstract

Advanced Packaging: From Strategic Imperative to Scalable Reality in Europe

Biography

Professional with over 25 years of experience in the semiconductor and advanced packaging sectors. Currently Senior Director at STATS ChipPAC, part of JCET Group, he has previously held leadership roles at STMicroelectronics and Infineon. He holds a degree in Electronics Engineering and a PhD in Microelectronics. His expertise spans R&D, business development, technology innovation, and strategic initiatives.

References